Dielectric filter 663MHz size 11.4x10.75mm

MODEL NO.: TR0030A REV. NO.:1

A. MAXIMUM RATING:

1. Input Power Level: 1W max.
2. DC Voltage : 0 V
3. Operating Temperature: -40℃ to +85℃
4. Storage Temperature:-40℃ to +85℃
5. Input/output impedance: 50 Ω
6. Moisture Sensitive Level: Level 2a (MSL2a)

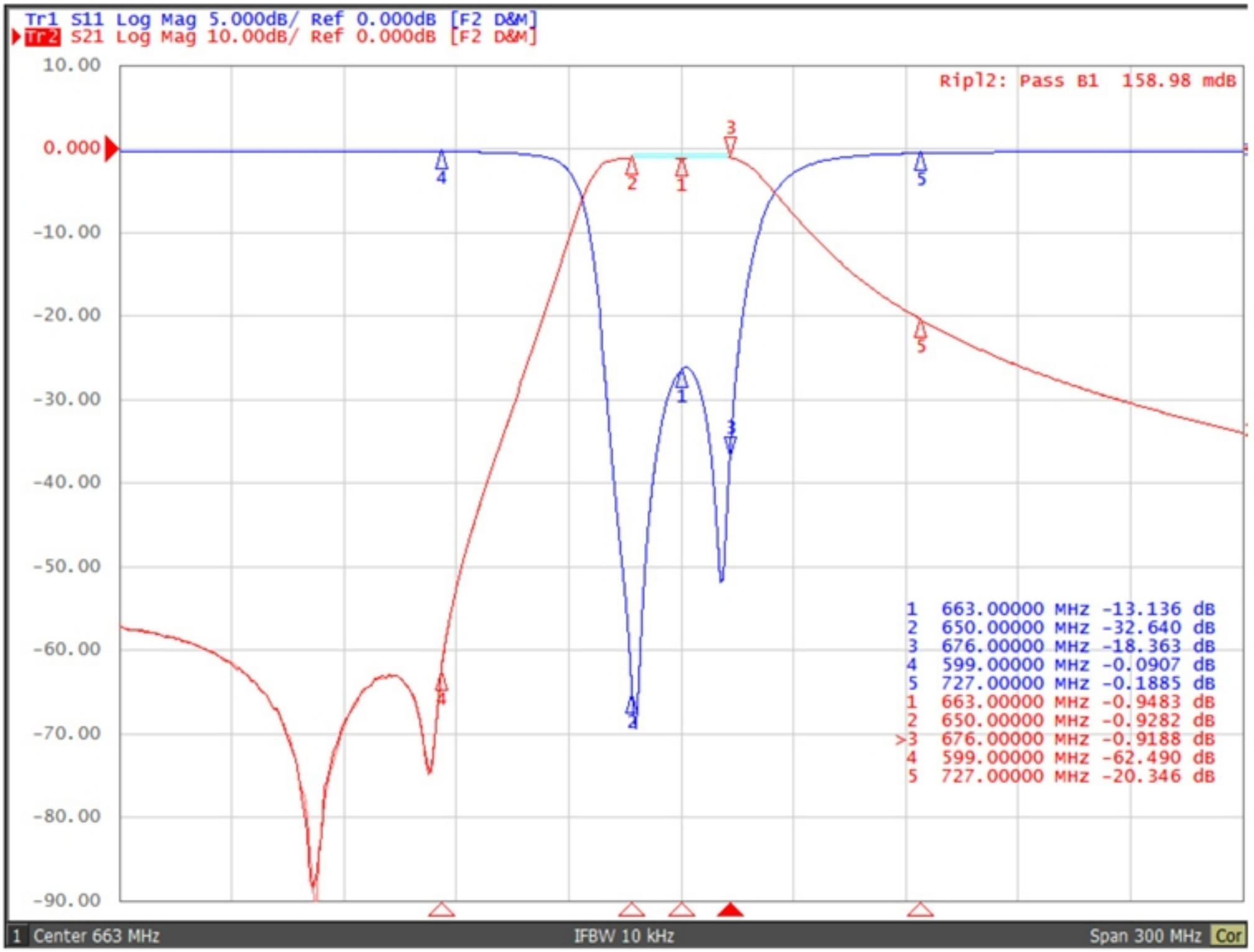
Electrostatic Sensitive Device (**ESD**)

B. ELECTRICAL CHARACTERISTICS:

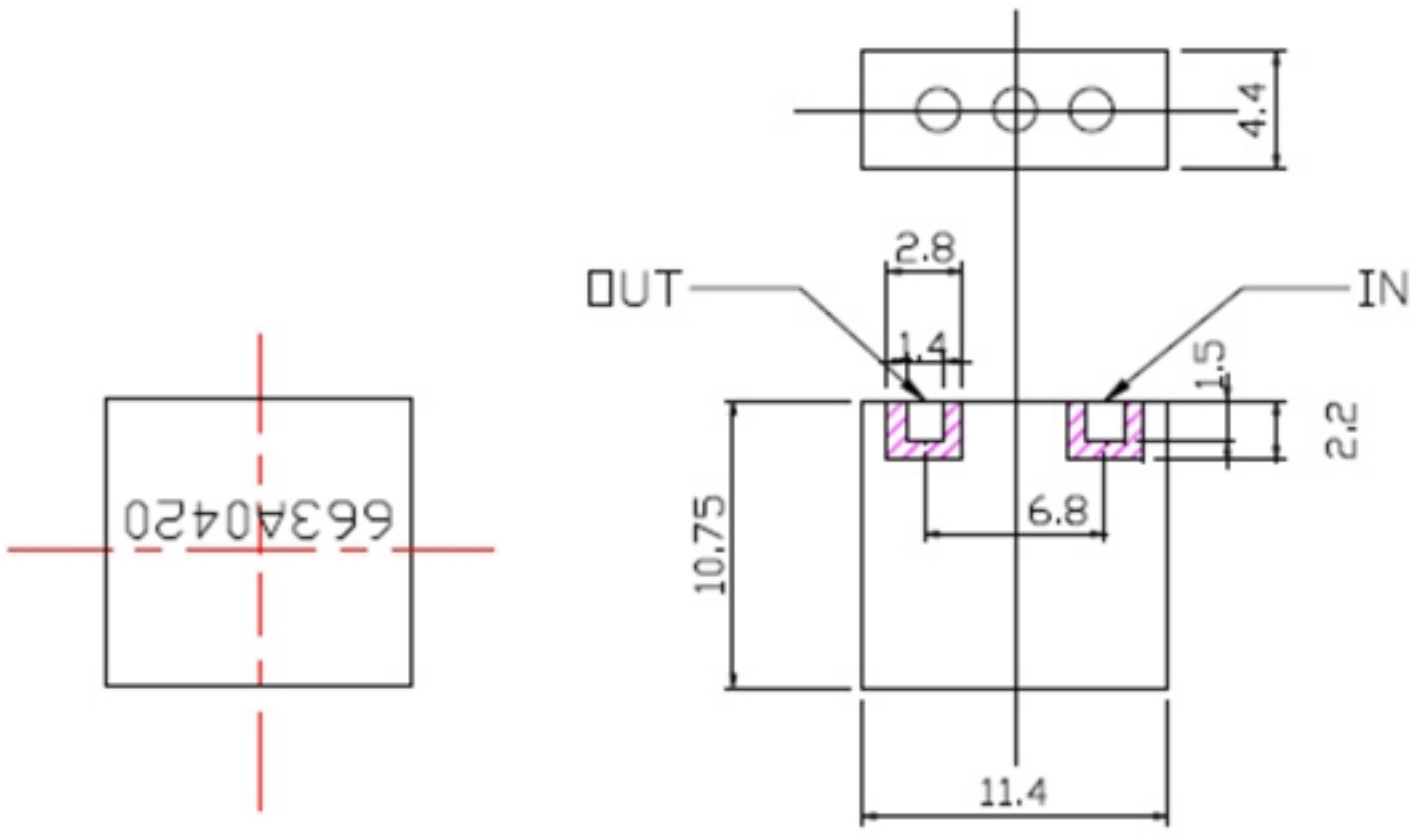
NO.	ITEM		SPECIFICATION	
			Min	Max
1	CENTER FREQUENCY		663MHz	
2	PASS BAND WIDTH		650 ~ 676MHz	
3	PASS BAND INSERTION LOSS			1.5 dB
4	PASS BAND RIPPLE			0.6 dB
5	PASS BAND RETURN LOSS		10 dB	
6	STOP-BAND ATTENUATION	599MHz	40 dB	
		727MHz	15 Db	
Item NO.6 specifies the absolute value of attenuation.				

※Data is measured on Cirocomm EVB board

C. FREQUENCY CHARACTERISTICS:



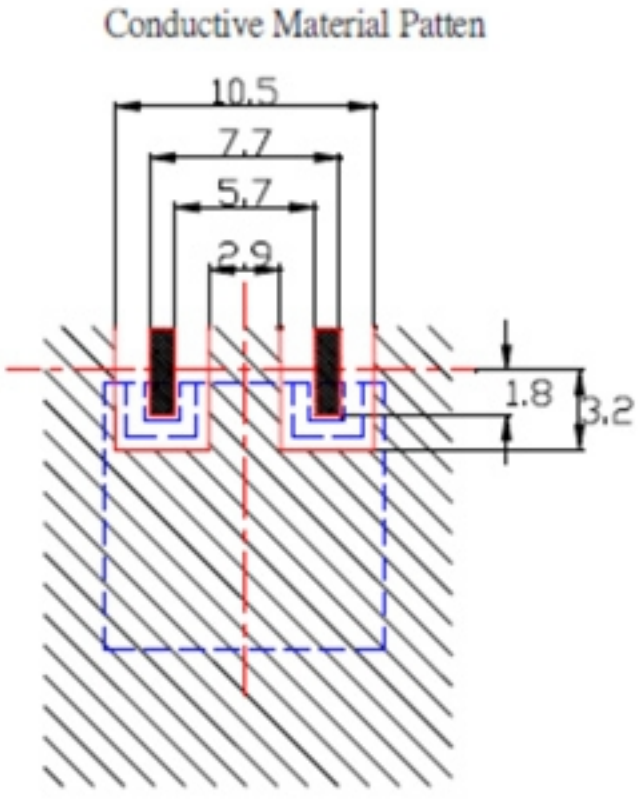
D. DIMENSION:

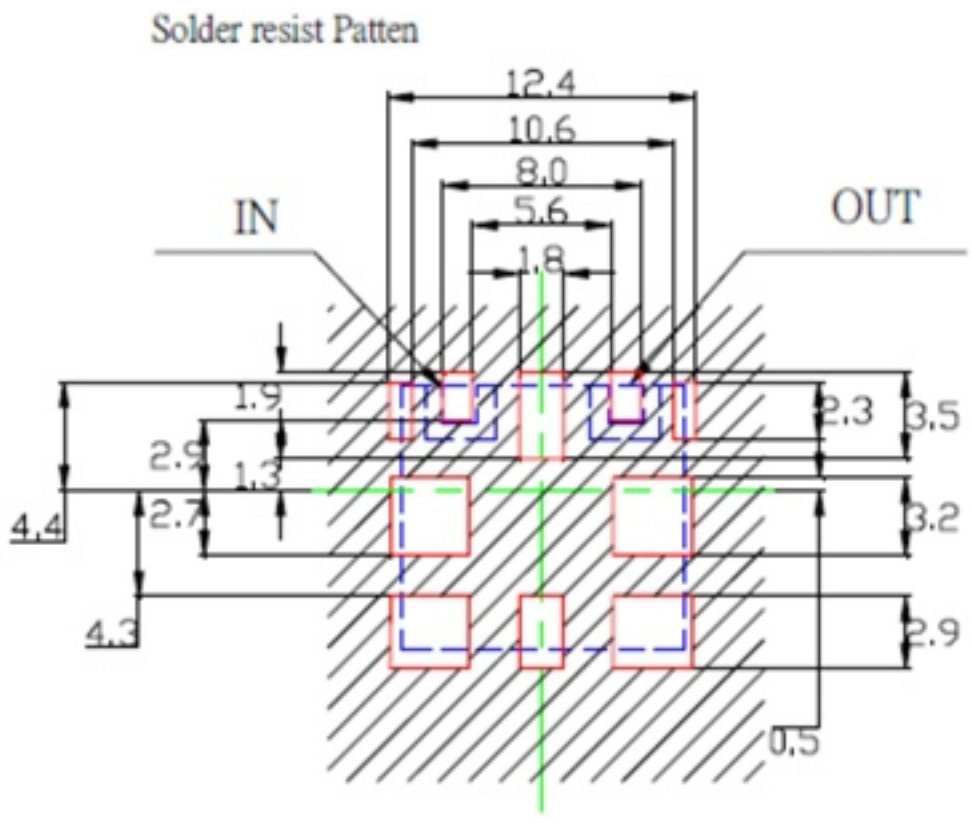


unit: mm
Tolerance:±0.3

663A : product name(J663A)
04 : month
20 : year (2020)

E. PCB FOOTPRINT:





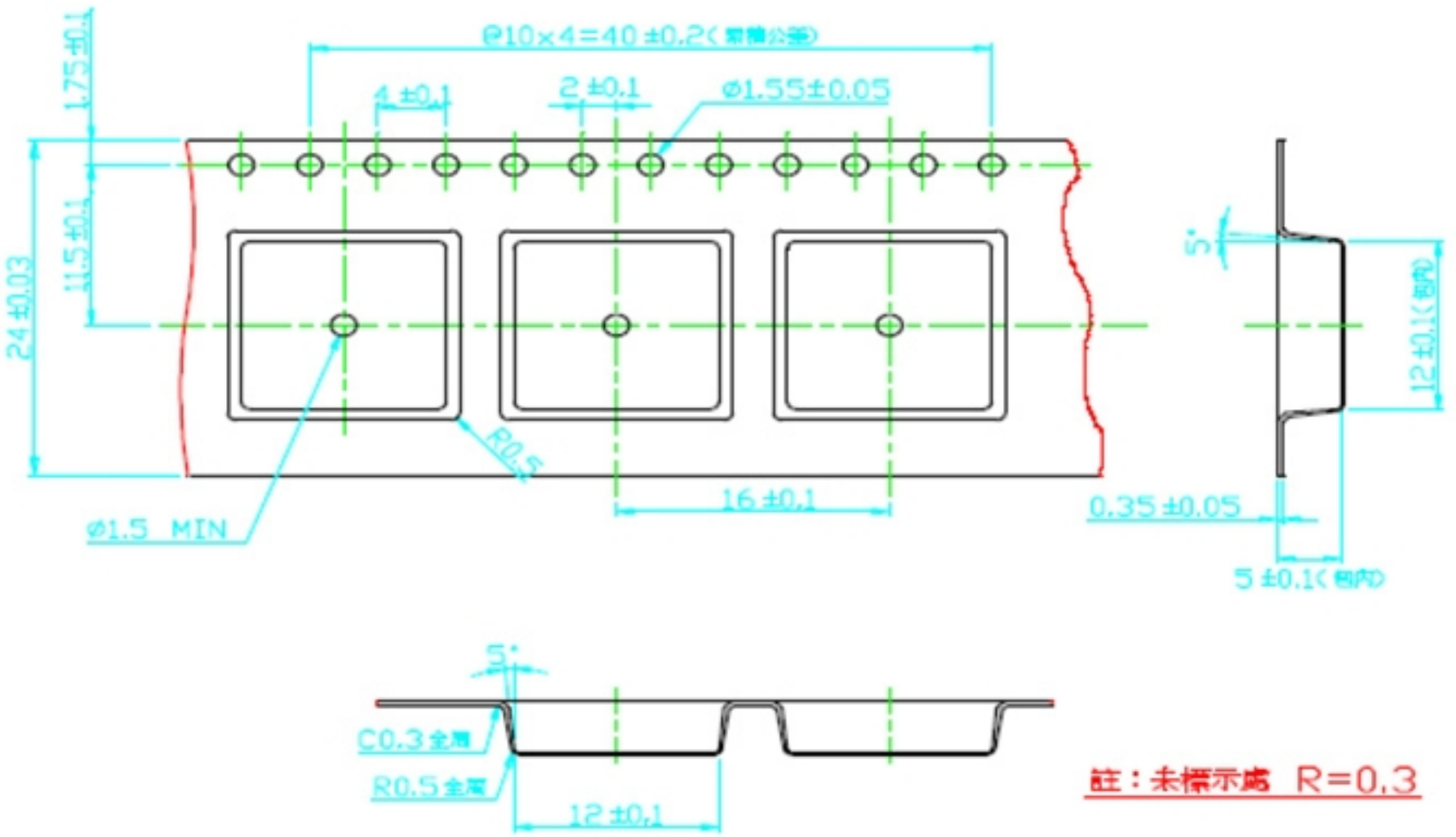
Conductive Material: Ground, connected to lower ground diameter of 0.6mm and max.distance of 3.0 mm.

I/O Pads must be connected to lineswith 50Ω impedance. in the application a termination of 50Ω must be realized.

unit : mm
Tolerance: ±0.1

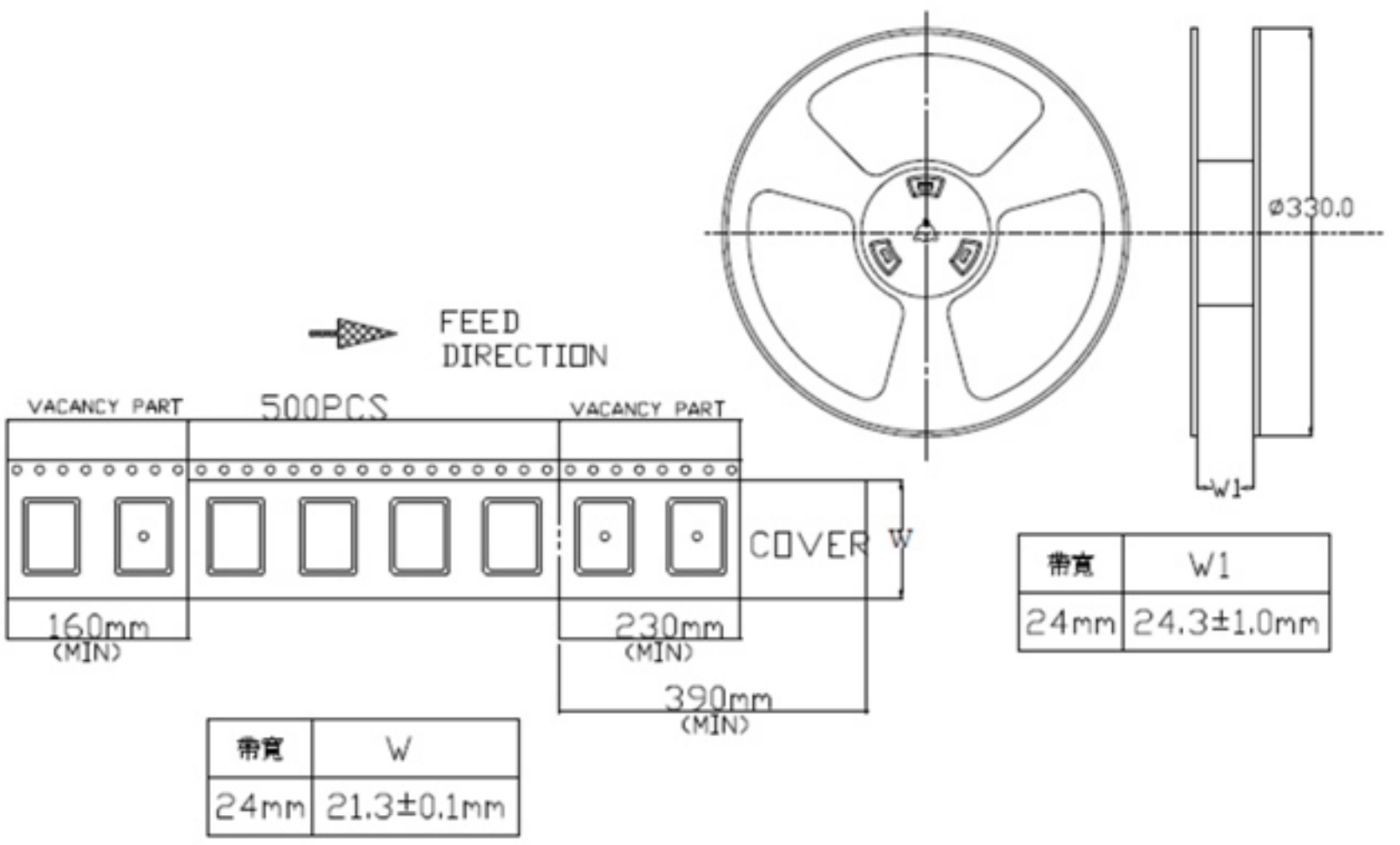
covered with solder resist.

F. PACKING:



註：未標示處 R=0.3

Reel



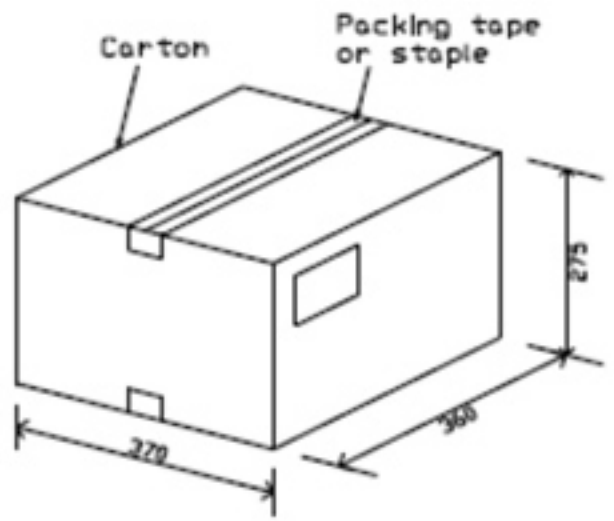
帶寬	W
24mm	21.3±0.1mm

帶寬	W1
24mm	24.3±1.0mm

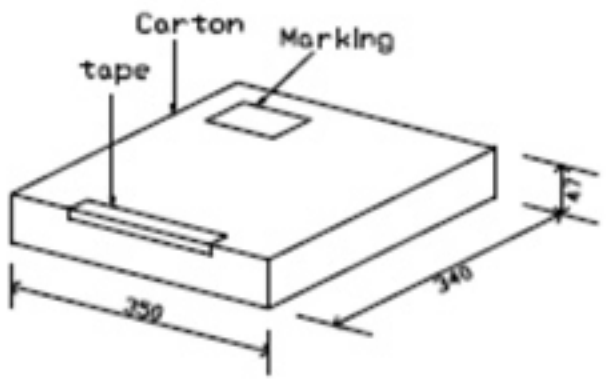
Package style

Moisture Sensitivity Level: Level 2a (MSL2a)

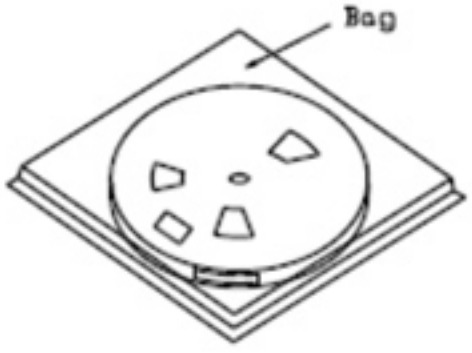
1. Outer Carton
   Quanylty:2500PCS



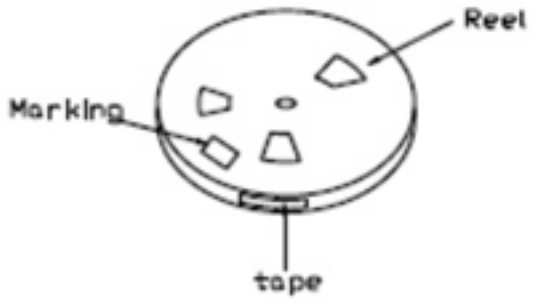
2. Inner Carton
   Quanylty:500PCS



3. Bag
   Quanylty:500PCS



4. Taping
   Quanylty:500PCS



Unit:mm

G. RECOMMENDED REFLOW PROFILE:

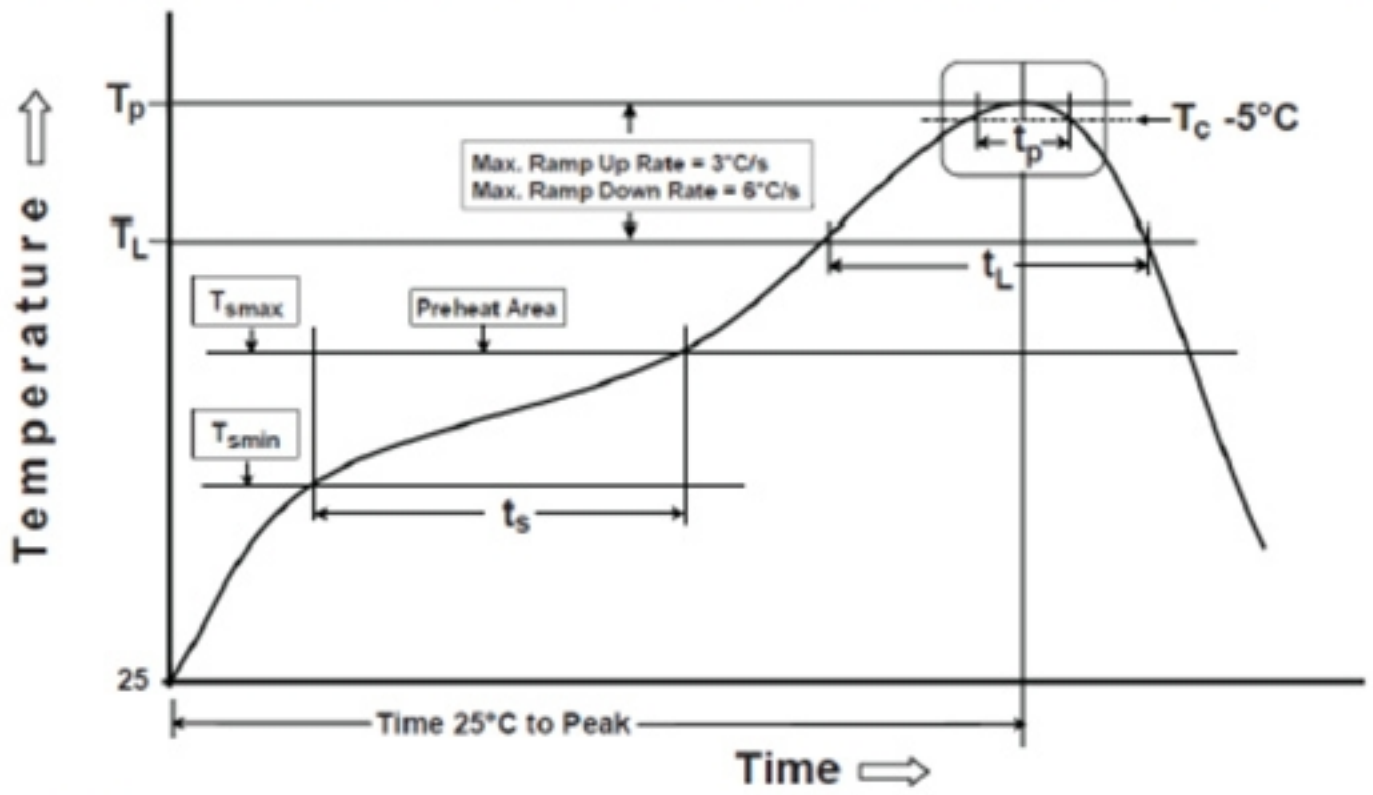
Recommended Reflow Soldering Profile

Cirocomm products can be assembled following Pb-free assembly. According to the Standard **IPC/JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150℃ 200℃ 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3℃/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217℃ 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260℃ 3 second
RAMP-DOWN	Rate	6℃ / second max.
Time from 25℃ to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note：All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

Soldering condition : Soldering iron temperature 270±10 ℃.

Apply preheating at 120℃ for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature 270±10 ℃ or 3 seconds, it will make component surface peeling or damage.

Soldering iron can not leakage of electricity.